3.4mm RIGHT ANGLE LED INDICATOR

Part Number: WP1384AL/ID

High Efficiency Red

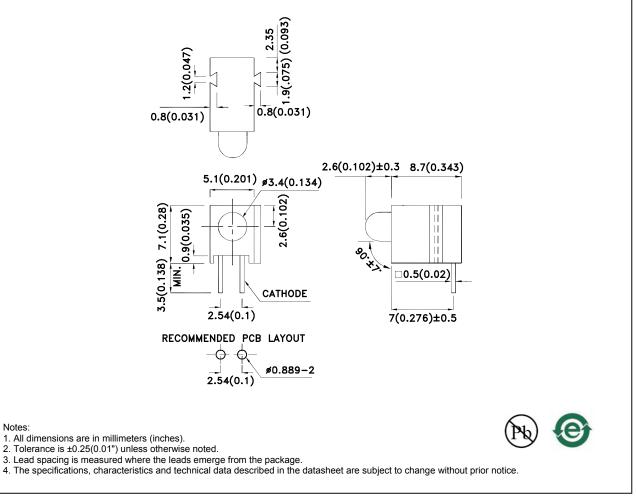
Features

- Pre-trimmed leads for pc mounting.
- Can be assembled with each other.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability-life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



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Selection Guide

Part No.	Dice	Dice Lens Type Iv (mcd) [2] @ 10mA		· • •	Viewing Angle [1]
			Min.	Тур.	201/2
WP1384AL/ID	High Efficiency Red (GaAsP/GaP)	Red Diffused	15	32	60°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I⊧=20mA	
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I⊧=20mA	
lr	Reverse Current	High Efficiency Red		10	uA	VR = 5V	

Notes:

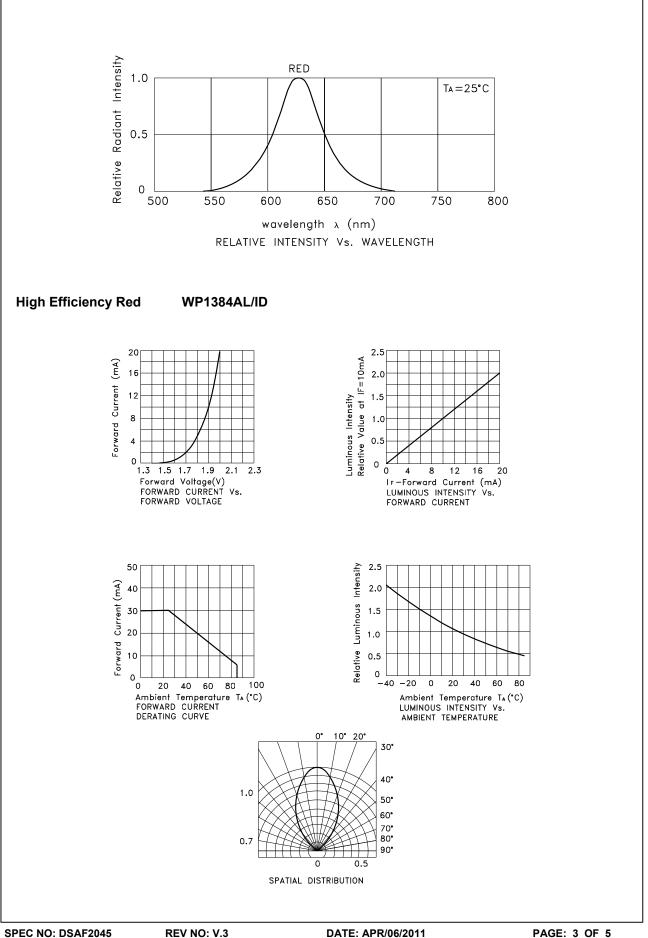
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

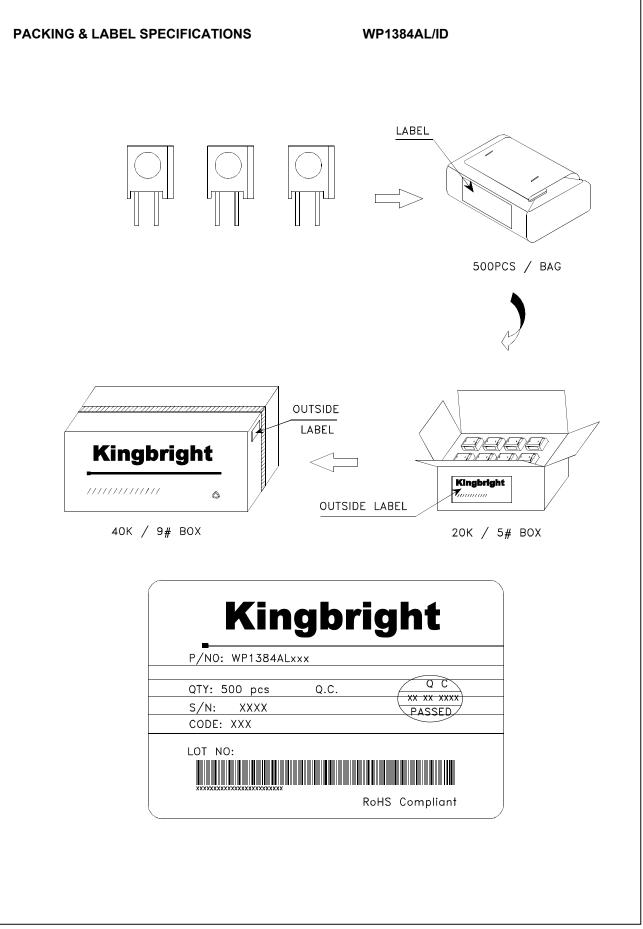
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30		
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

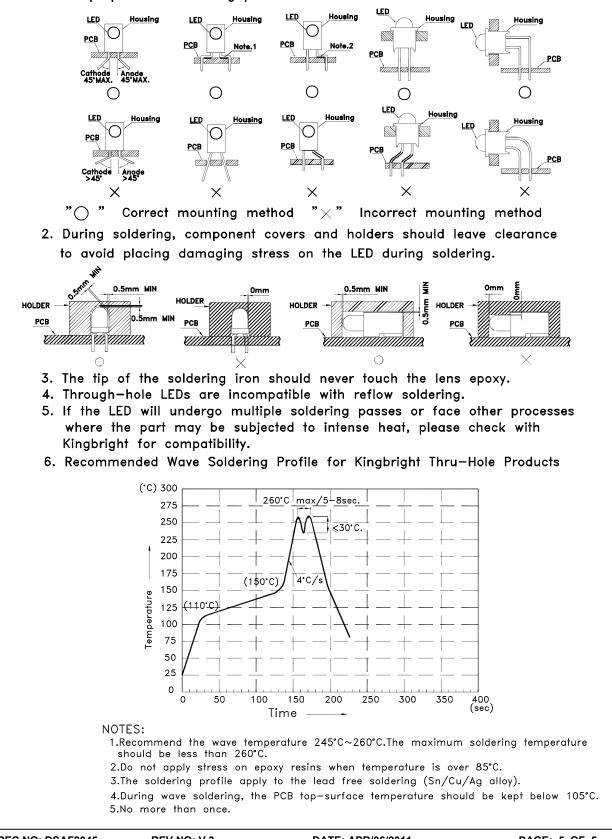
1.1/10 Duty Cycle, 0.1ms Pulse Width.
2.2mm below package base.
3.5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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